

RoHS Compliant Product  
A suffix of "-C" specifies halogen free

## DESCRIPTION

This advanced high voltage MOSFET is designed to Withstand high energy in the avalanche mode and switch efficiently. This new high energy device also offers a drain to source diode with fast recovery time. Designed for high voltage, high speed switching applications such as power supplies, converters, power motor controls and bridge circuits.

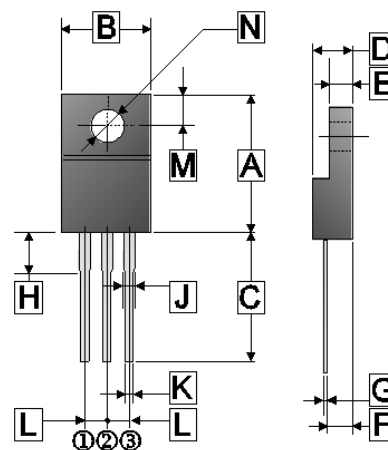
## FEATURES

- High current rating
- Lower  $R_{DS(ON)}$
- Lower capacitance
- Lower total gate charge
- Tighter VSD specifications
- Specified avalanche energy

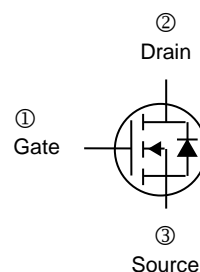
## ORDER INFORMATION

Part Number	Type
SSQF04N60J-C	Lead (Pb)-free and Halogen-free

ITO-220J



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	14.50	15.50	H	3.80	TYP.
B	9.50	10.50	J	1.30	REF.
C	13.20	REF.	K	0.30	0.90
D	4.24	4.84	L	2.54	REF.
E	2.52	3.20	M	2.70	REF.
F	2.50	2.90	N	$\phi$ 3.50	REF.
G	0.47	0.75			



## ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	600	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current	$I_D$	4	A
Continuous Drain-Source Diode Forward Current	$I_S$	4	A
Maximum Lead Temperature for Soldering Purposes @ 1/8" from case for 5 seconds	$T_L$	260	$^\circ\text{C}$
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~150	$^\circ\text{C}$
<b>Thermal Resistance Rating</b>			
Thermal Resistance from Junction-Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$

**ELECTRICAL CHARACTERISTICS** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

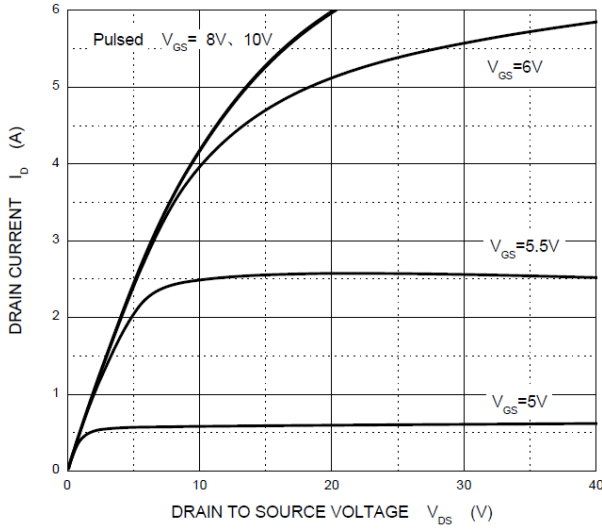
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Drain-Source Breakdown Voltage	$B_{V_{DS}}$	600	645	-	V	$V_{GS}=0, I_D=250\mu\text{A}$
Gate-Threshold Voltage <sup>1</sup>	$V_{GS(th)}$	2	3	4	V	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$
Forward Transconductance <sup>1</sup>	$g_{fs}$	2	2.6	-	S	$V_{DS}=50\text{V}, I_D=2\text{A}$
Gate-Source Forward Leakage Current <sup>1</sup>	$I_{GSSF}$	-	-	100	nA	$V_{DS}=0\text{V}, V_{GS}=30\text{V}$
Gate-Source Reverse Leakage Current <sup>1</sup>	$I_{GSSR}$	-	-	-100	nA	$V_{DS}=0\text{V}, V_{GS}=-30\text{V}$
Drain-Source Leakage Current	$I_{DSS}$	-	-	25	$\mu\text{A}$	$V_{DS}=600\text{V}, V_{GS}=0$
Static Drain-Source On-Resistance <sup>1</sup>	$R_{DS(ON)}$	-	2	2.4	$\Omega$	$V_{GS}=10\text{V}, I_D=2\text{A}$
Gate Resistance	$R_g$	-	2.3	-	$\Omega$	$f=1\text{MHz}$
Total Gate Charge	$Q_g$	-	5	-	nC	$V_{DS}=480\text{V}$ $V_{GS}=10\text{V}$ $I_D=4\text{A}$
Gate-Source Charge	$Q_{gs}$	-	2.7	-		
Gate-Drain Charge	$Q_{gd}$	-	2	-		
Turn-on Delay Time	$T_{d(on)}$	-	12	-	nS	$V_{DD}=300\text{V}$ $V_{GS}=10\text{V}$ $R_G=9.1\Omega$ $I_D=4\text{A}$
Rise Time	$T_r$	-	7	-		
Turn-off Delay Time	$T_{d(off)}$	-	19	-		
Fall Time	$T_f$	-	10	-		
Input Capacitance	$C_{iss}$		540	-	pF	$V_{DS}=25\text{V}$ $V_{GS}=0$ $f=1\text{MHz}$
Output Capacitance	$C_{oss}$		125	-		
Reverse Transfer Capacitance	$C_{rss}$		8	-		
Diode Forward Voltage <sup>1</sup>	$V_{SD}$	-	0.83	1.5	V	$V_{GS}=0, I_S=4\text{A}$

Note:

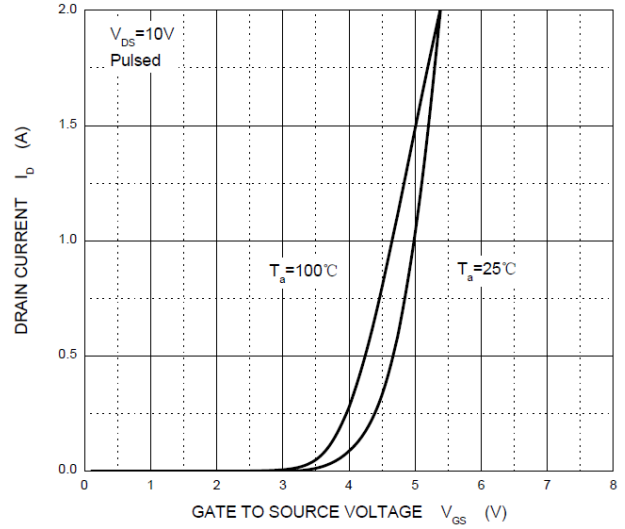
1. Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .

**CHARACTERISTIC CURVES**

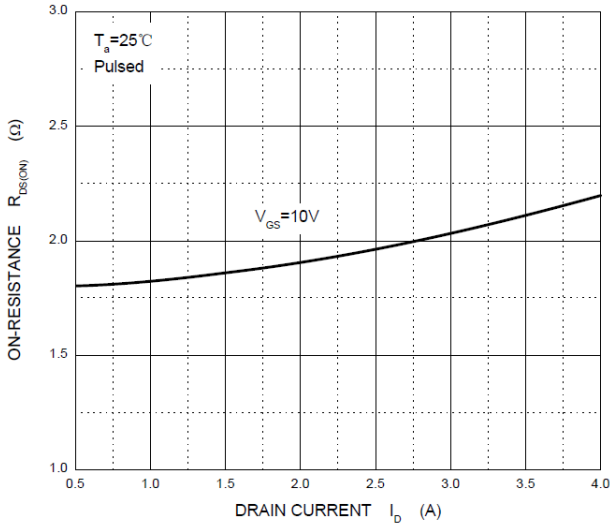
Output Characteristics



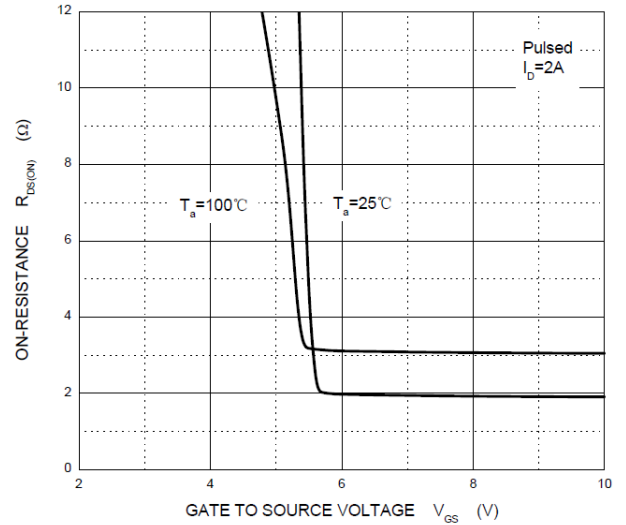
Transfer Characteristics



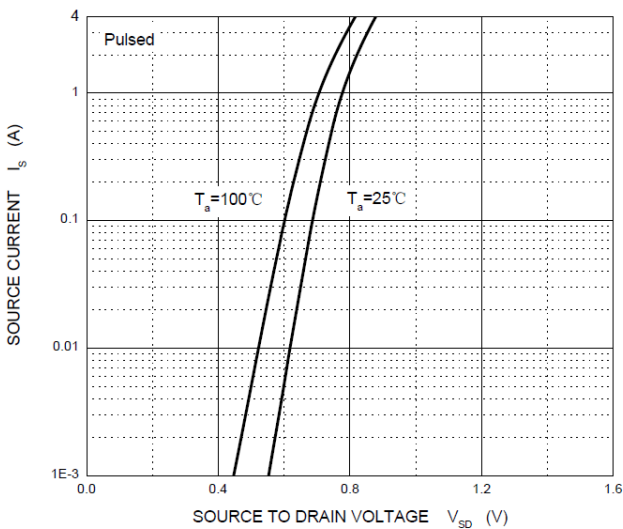
$R_{DS(ON)}$  —  $I_D$



$R_{DS(ON)}$  —  $V_{GS}$



$I_S$  —  $V_{SD}$



Threshold Voltage

